

PLEASE CHECK WWW.MOLEX.COM FOR LATEST PART INFORMATION

Part Number: [0780790012](#)
Status: **Active**
Description: 1.00mm (.039") Pitch DDR3 DIMM Socket, Vertical, Through Hole, with Beveled Metal Pins, Black Housing and Latches, 0.76µm (30µ") Gold (Au) Plating, 3.18mm(.125") Solder tail, 240 Circuits, Lead free

Documents:

[3D Model](#) [Product Specification PS-78079-002 \(PDF\)](#)
[Drawing \(PDF\)](#) [RoHS Certificate of Compliance \(PDF\)](#)

Agency Certification

CSA LR19980
 UL E29179

General

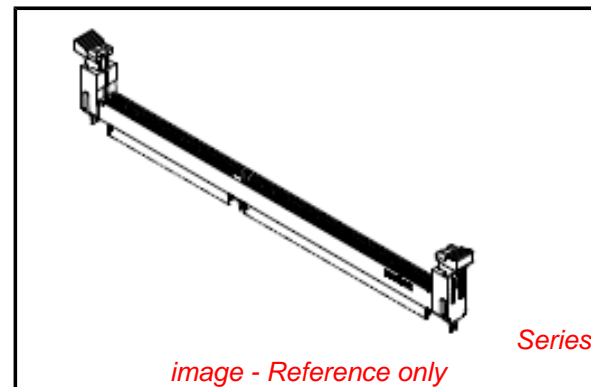
Product Family Memory Module Sockets
 Series [78079](#)
 Component Type Socket
 JEDEC Outline MO-269
 Product Name DDR3 DIMM

Physical

Circuits (Loaded) 240
 Circuits (maximum) 240
 Color - Resin Black
 Durability (mating cycles max) 25
 Entry Angle Vertical
 Flammability 94V-0
 Function Key None
 Keying to Mating Part Yes
 Material - Metal Copper Alloy
 Material - Plating Mating Gold
 Material - Plating Termination Tin
 Material - Resin High Temperature Thermoplastic
 PC Tail Length (in) 0.125 In
 PC Tail Length (mm) 3.18 mm
 PCB Locator Yes
 PCB Retention Yes
 PCB Thickness Recommended (in) 0.093 In
 PCB Thickness Recommended (mm) 2.36 mm
 Packaging Type Tray
 Pitch - Mating Interface (in) 0.039 In
 Pitch - Mating Interface (mm) 1.00 mm
 Pitch - Term. Interface (in) 0.039 In
 Pitch - Term. Interface (mm) 1.00 mm
 Plating min: Mating (µin) 30
 Plating min: Mating (µm) 0.76
 Plating min: Termination (µin) 100
 Plating min: Termination (µm) 2.54
 Temperature Range - Operating -55°C to +85°C
 Termination Interface: Style Through Hole

Electrical

Current - Maximum per Contact 1A
 Voltage - Maximum 30V AC (RMS)/DC
 Voltage Key Center



EU RoHS

ELV and RoHS Compliant
REACH SVHC
 Not Reviewed
Halogen-Free Status
Not Reviewed

China RoHS



Need more information on product environmental compliance?

Email productcompliance@molex.com
 For a multiple part number RoHS Certificate of Compliance, [click here](#)

Please visit the [Contact Us](#) section for any non-product compliance questions.

Search Parts in this Series

[78079Series](#)

Mates With

JEDEC standard 1.27mm modules

Solder Process Data

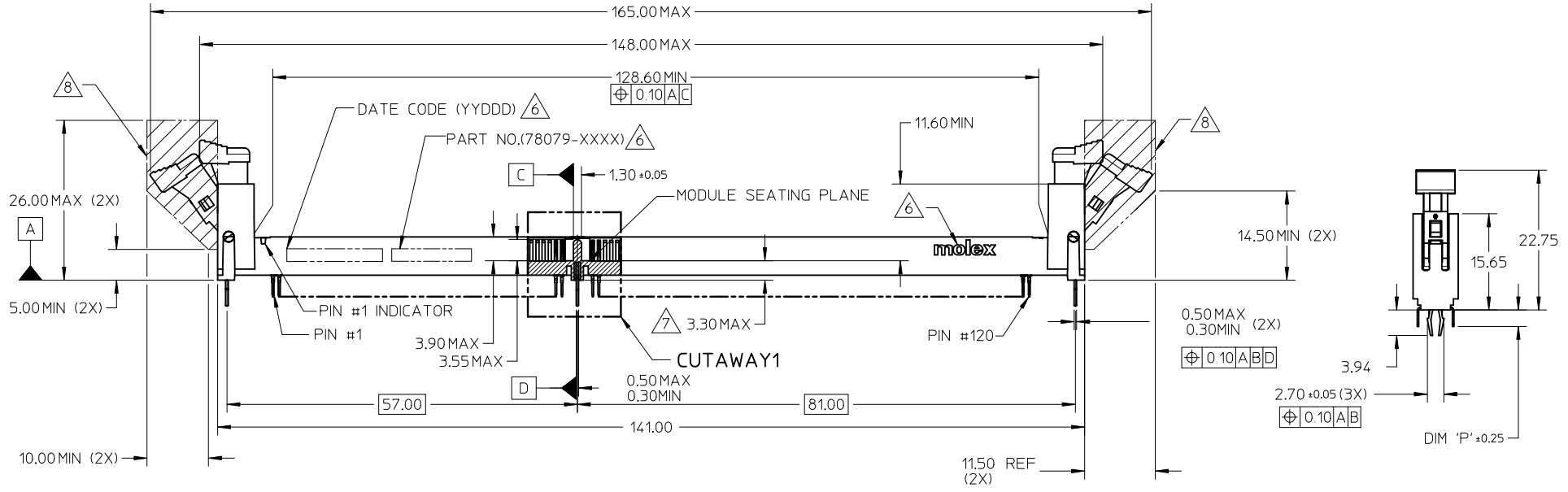
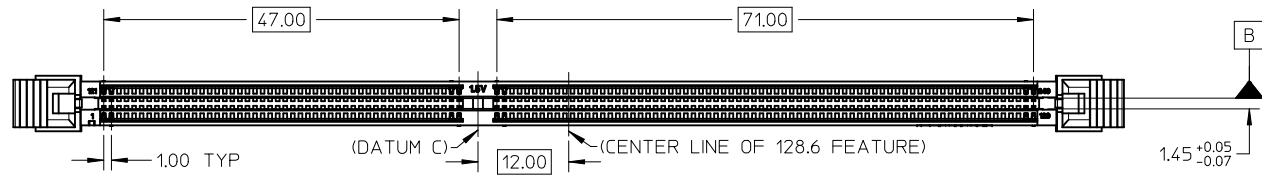
Duration at Max. Process Temperature (seconds)	5
Lead-free Process Capability	SMC & Wave Capable (TH only)
Max. Cycles at Max. Process Temperature	2
Process Temperature max. C	260

Material Info**Reference - Drawing Numbers**

Product Specification	PS-78079-002
Sales Drawing	SD-78079-001

This document was generated on 04/16/2010

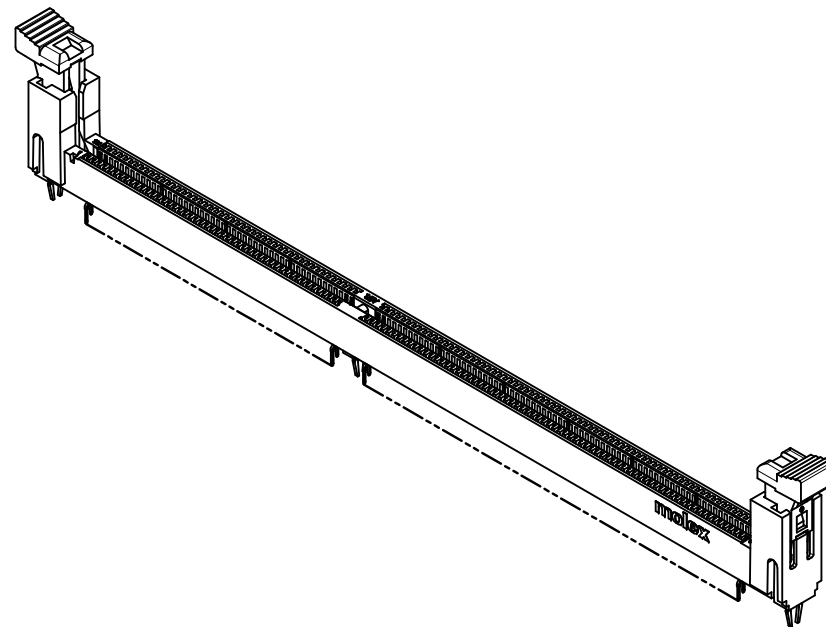
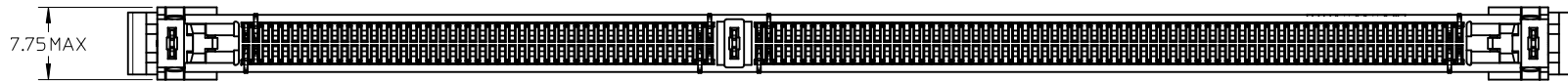
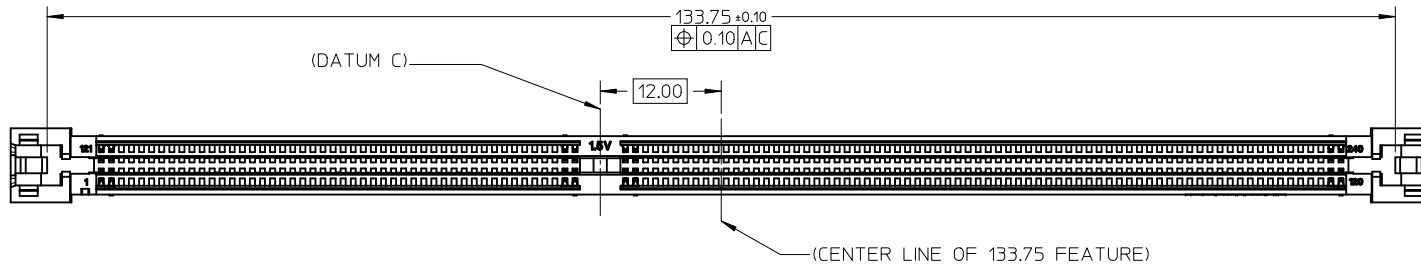
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- NOTES :
- MATERIAL : HOUSING - HIGH TEMP. NYLON, GLASS FILLED, UL 94V-0
COLOUR : SEE SHEET 6 AND 7
LATCH - HIGH TEMP NYLON, GLASS FILLED, UL 94V-0
COLOUR : SEE SHEET 6 AND 7
TERMINAL : COPPER ALLOY.
 - TERMINAL PLATING OPTIONS: SEE TABLE ON SHEETS 6 & 7.
 - PRODUCT SPECIFICATION: SEE TABLE ON SHEETS 6 & 7.
 - PACKAGING INFORMATION: PRODUCT SHALL BE PACKED IN TRAY
 - CARD SLOT ACCEPTS 1.27±0.10MM MODULE THICKNESS (MEASURED FROM P.C. PADS).
 - MOLEX LOGO, DATE & PART NO. INDICATED ON HOUSING.
 - MODULE SEATING PLANE FROM TOP OF PCB.
 - KEEP OUT ZONE RESERVED FOR LATCH.

FORKLOCK UPDATED EC NO: S2010-0888 DRWN: JAKEEWEW 2010/04/29 CHKD: CCTEH 2010/06/10 APPR: SHLENI 2010/06/13	QUALITY SYMBOLS $F_A=0$ $F_C=0$ $F_P=0$	GENERAL TOLERANCES (UNLESS SPECIFIED) <table border="1"> <thead> <tr> <th></th> <th>mm</th> <th>INCH</th> </tr> </thead> <tbody> <tr> <td>4 PLACES</td> <td>± ---</td> <td>± ---</td> </tr> <tr> <td>3 PLACES</td> <td>± ---</td> <td>± ---</td> </tr> <tr> <td>2 PLACES</td> <td>± 0.2</td> <td>± ---</td> </tr> <tr> <td>1 PLACE</td> <td>± ---</td> <td>± ---</td> </tr> </tbody> </table>		mm	INCH	4 PLACES	± ---	± ---	3 PLACES	± ---	± ---	2 PLACES	± 0.2	± ---	1 PLACE	± ---	± ---	DIMENSION STYLE MM ONLY	SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
		mm	INCH																		
	4 PLACES	± ---	± ---																		
	3 PLACES	± ---	± ---																		
2 PLACES	± 0.2	± ---																			
1 PLACE	± ---	± ---																			
		DRAWN BY YTYANG01	DATE 2006/08/11	TITLE DDR3 DIMM, 100MM PITCH 240 CKTS, VERTICAL T/H																	
		CHECKED BY SHLENI	DATE 2006/09/07	MOLEX INCORPORATED																	
		APPROVED BY SHLENI	DATE 2010/06/10	MATERIAL NO. SEE TABLE	DOCUMENT NO. SD-78079-001	SHEET NO. 1 OF 8															

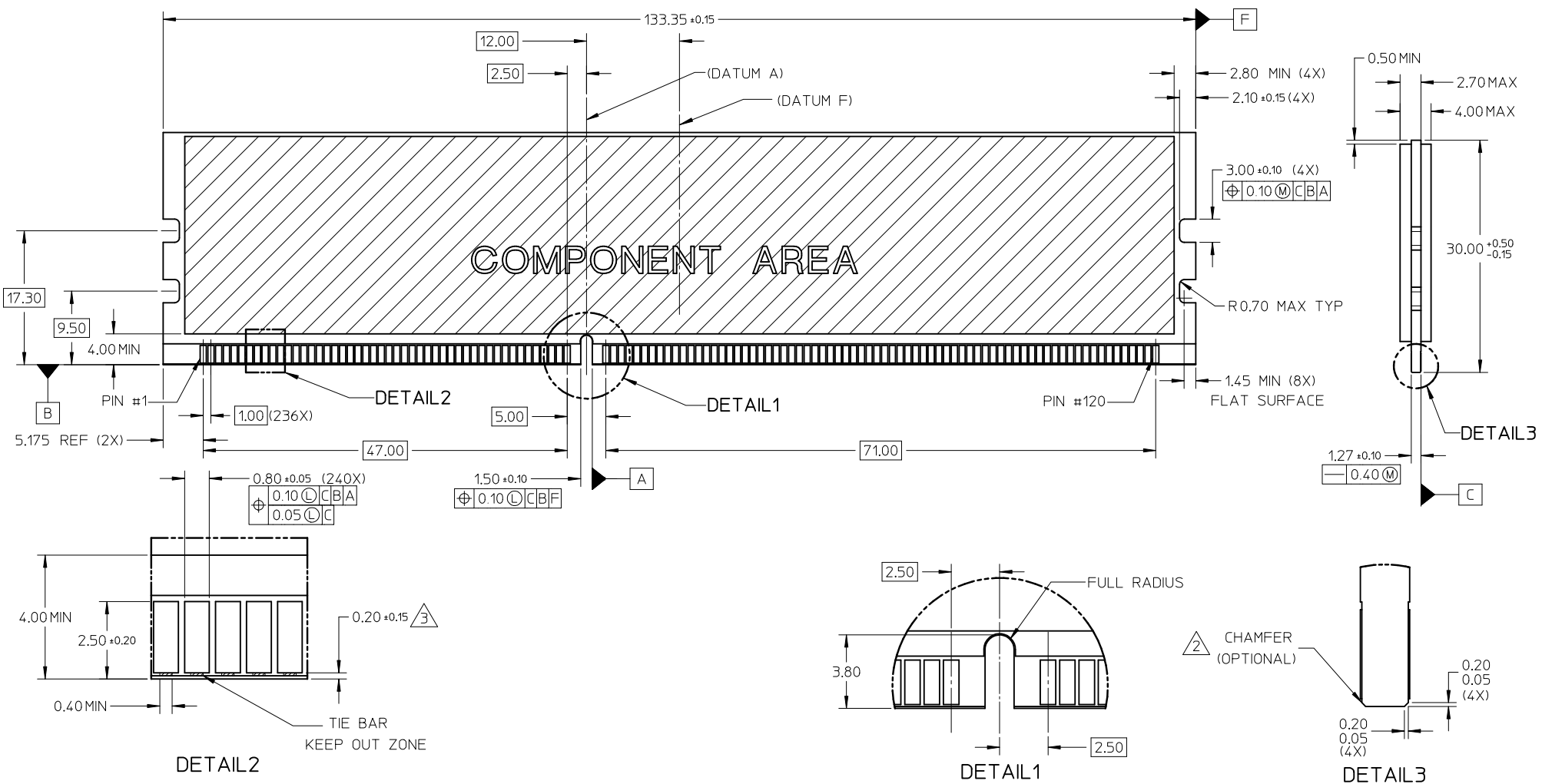
10 9 8 7 6 5 4 3 2 1



FORKLOCK UPDATED EC NO: S2010-0888 DRWN: JAKEEWEW 2010/04/29 CHKD: CCTEH 2010/06/10 APPR: SHLENI 2010/06/13	QUALITY SYMBOLS $\nabla_A = 0$ $\nabla_C = 0$ $\nabla_P = 0$	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
			mm	INCH	DRAWN BY YTYANG01	DATE 2006/08/11	TITLE DDR3 DIMM, 100MM PITCH 240 CKTS, VERTICAL T/H			
		4 PLACES	± ---	± ---	CHECKED BY SHLENI	DATE 2006/09/07	MOLEX INCORPORATED DOCUMENT NO. SD-78079-001			
		3 PLACES	± ---	± ---	APPROVED BY SHLENI	DATE 2010/06/10				
2 PLACES	± 0.2	± ---	ANGULAR ± 1 °		SEE TABLE		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			
1 PLACE	± ---	± ---	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3					

9 8 7 6 5 4 3 2 1

MODULE CARD
 DDR3 DUAL IN-LINE MEMORY MODULE FAMILY 1.00MM CONTACT CENTERS
 (JEDEC MO-269, ISSUE B, MAY 06)



- NOTES:
- RECOMMENDED PLATING FOR CONTACT PADS:
 PREFERRED: 0.76 MICROMETERS GOLD PLATING MIN OVER 2.00 MICROMETERS NICKEL
 ALTERNATIVE: 0.05-0.75 MICROMETERS GOLD PLATING OVER 2.00 MICROMETERS NICKEL MUST USE AN ELECTRONIC CONTACT GRADE CORROSIVE BARRIER LUBRICANT
 - CHAMFER IS OPTIONAL AND IS NOT TO HIT THE GOLD PADS
 - LEADING EDGE OF GOLD PADS SPECIFIED BY KEEPOUT ZONE SHALL BE FREE OF BURRS AND EXTERNAL TIE BARS.

FORKLOCK UPDATED EC NO: S2010-0888 DRWN: JAKEEWEW 2010/04/29 CHYK: CCTEH 2010/06/10 APPR: SHLENI 2010/06/13	QUALITY SYMBOLS $F_A=0$ $F_C=0$ $F_B=0$	GENERAL TOLERANCES (UNLESS SPECIFIED) mm INCH 4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.2 ± --- 1 PLACE ± --- ± --- ANGULAR ± 1°	DIMENSION STYLE MM ONLY DRAWN BY DATE YTYANG01 2006/08/11 CHECKED BY DATE SHLENI 2006/09/07 APPROVED BY DATE SHLENI 2010/06/10	SCALE NTS TITLE DDR3 DIMM, 1.00MM PITCH 240 CKTS, VERTICAL T/H	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	MATERIAL NO. SEE TABLE	DOCUMENT NO. SD-78079-001	SHEET NO. 3 OF 8			
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			MOLEX INCORPORATED		
	SIZE A3 THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			MOLEX INCORPORATED		

10 9 8 7 6 5 4 3 2 1

KEEP OUT AREA

$\phi 0.12$ Z X
 $\phi 2.45 \pm 0.05$

13.00 REF

Y

PIN #121

PIN #1

7.50

DETAIL 4

5.00

47.00

57.00

6

164.00

141.00

5

4

$\phi 0.70 \pm 0.08$ TYP
 $\phi 0.10$ M Z X-Y

PIN #240

PIN #120

TYP 1.00

2.50

71.00

81.00

3

3.68 REF

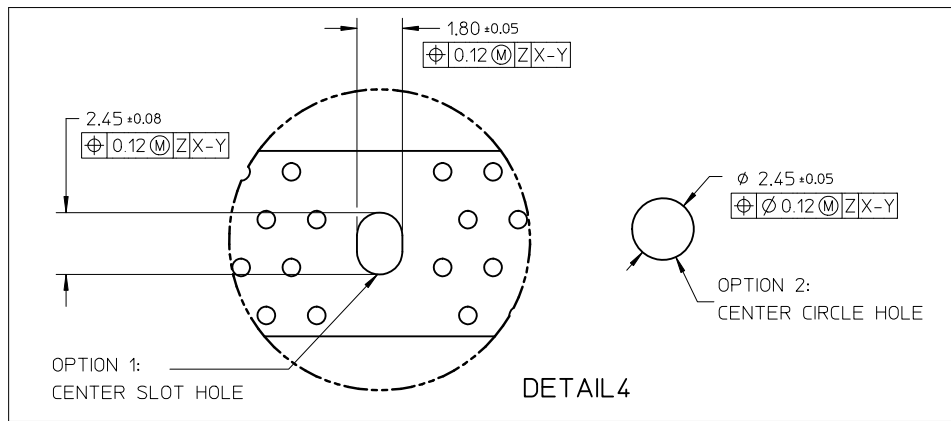
$\phi 2.45 \pm 0.05$

X

Z

0.95
(2X)

(2X)
2.85

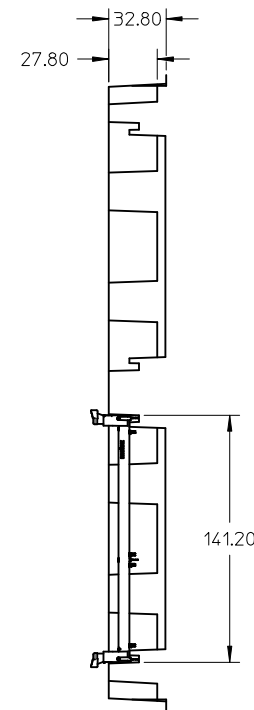
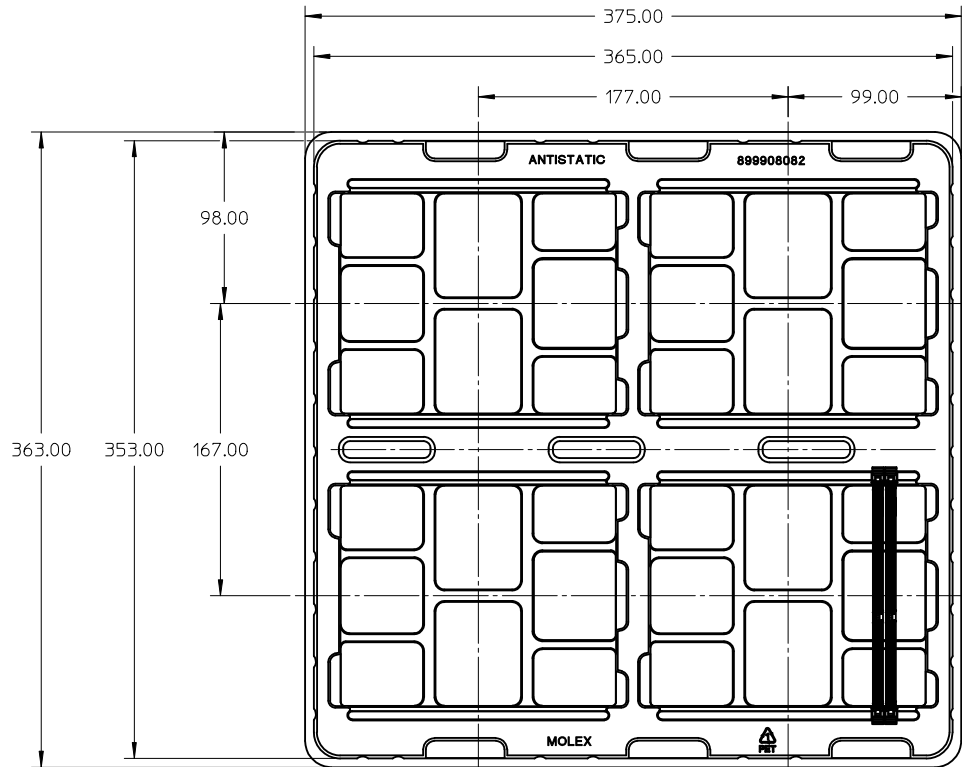


NOTE:
 1. KEEP OUT AREA IS THE AREA WHERE THE CONNECTOR (INCLUDING LATCH) IS MOUNTED ON THE PCB.

FORKLOCK UPDATED EC NO: S2010-0888 DRWN: JAKEEWEW 2010/04/29 CHKD: CTEH 2010/06/10 APPR: SHLENI 2010/06/13	QUALITY SYMBOLS $F_A=0$ $F_C=0$ $F_P=0$	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		mm	INCH	DRAWN BY	DATE	TITLE			
		± ---	± ---	YTYANG01	2006/08/11	DDR3 DIMM, 100MM PITCH			
		± ---	± ---	CHECKED BY	DATE	240 CKTS, VERTICAL T/H			
		± 0.2	± ---	SHLENI	2006/09/07	MOLEX INCORPORATED			
		± ---	± ---	APPROVED BY	DATE				
		± ---	± ---	SHLENI	2010/06/10	MATERIAL NO.		DOCUMENT NO.	
		ANGULAR ± 1 °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE		SD-78079-001	
A4	REV			SIZE	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				SHEET NO. 4 OF 8

9 8 7 6 5 4 3 2 1

10 9 8 7 6 5 4 3 2 1



NOTES:
1. QTY OF CAVITY: 20 X 4 = 80 PCS

FORKLOCK UPDATED EC NO: S2010-0888 DRWN: JAKEEWEW 2010/04/29 CHKD: CCTEH 2010/06/10 APPR: SHLENI 2010/06/13	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	$F_A=0$	4 PLACES	mm	INCH	DRAWN BY YTYANG01	DATE 2006/08/11	TITLE DDR3 DIMM, 100MM PITCH 240 CKTS, VERTICAL T/H		
	$F_C=0$	3 PLACES	± ---	± ---	CHECKED BY SHLENI	DATE 2006/09/07	MATERIAL NO. SEE TABLE		
	$F_P=0$	2 PLACES	± 0.2	± ---	APPROVED BY SHLENI	DATE 2010/06/10	DOCUMENT NO. SD-78079-001		
		1 PLACE	± ---	± ---	ANGULAR ± 1 °		MOLEX INCORPORATED		SHEET NO. 5 OF 8
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			

9 8 7 6 5 4 3 2 1


ASSEMBLY PART NO.	VOLTAGE KEY	HOUSING COLOR	LATCH COLOR	DIM 'P'	RECOMMENDED PCB THICKNESS	PLATING OPTION	PRODUCT SPECIFICATION		
78079-0001	CENTRE (1.5V)	BLACK	BLACK	2.67	1.57	0.38 MICROMETER/ 15 MICROINCH MIN. GOLD ON CONTACT 2.54 MICROMETER/ 100 MICROINCH MIN. PURE TIN ON SOLDER TAILS 1.27 MICROMETER/ 50 MICROINCH MIN. NICKEL UNDERPLATE	PS-78079-001		
78079-0003				3.00	2.18				
78079-0002				3.18	2.36				
78079-0011				2.67	1.57	0.76 MICROMETER/ 30 MICROINCH MIN. GOLD ON CONTACT 2.54 MICROMETER/ 100 MICROINCH MIN. PURE TIN ON SOLDER TAILS 1.27 MICROMETER/ 50 MICROINCH MIN. NICKEL UNDERPLATE		PS-78079-002	
78079-0013				3.00	2.18				
78079-0012				3.18	2.36				
78079-0021				2.67	1.57	0.076 MICROMETER/ 3 MICROINCH MIN. GOLD ON CONTACT 2.54 MICROMETER/ 100 MICROINCH MIN. PURE TIN ON SOLDER TAILS 1.27 MICROMETER/ 50 MICROINCH MIN. NICKEL UNDERPLATE		PS-78079-003	
78079-0023				3.00	2.18				
78079-0022				3.18	2.36				
78079-0051			NATURAL (OFFWHITE)		BLACK	2.67	1.57	0.38 MICROMETER/ 15 MICROINCH MIN. GOLD ON CONTACT 2.54 MICROMETER/ 100 MICROINCH MIN. PURE TIN ON SOLDER TAILS 1.27 MICROMETER/ 50 MICROINCH MIN. NICKEL UNDERPLATE	PS-78079-001
78079-0053						3.00	2.18		
78079-0052						3.18	2.36		
78079-0061					2.67	1.57	0.76 MICROMETER/ 30 MICROINCH MIN. GOLD ON CONTACT 2.54 MICROMETER/ 100 MICROINCH MIN. PURE TIN ON SOLDER TAILS 1.27 MICROMETER/ 50 MICROINCH MIN. NICKEL UNDERPLATE	PS-78079-002	
78079-0063					3.00	2.18			
78079-0062					3.18	2.36			
78079-0071					2.67	1.57	0.076 MICROMETER/ 3 MICROINCH MIN. GOLD ON CONTACT 2.54 MICROMETER/ 100 MICROINCH MIN. PURE TIN ON SOLDER TAILS 1.27 MICROMETER/ 50 MICROINCH MIN. NICKEL UNDERPLATE	PS-78079-003	
78079-0073					3.00	2.18			
78079-0072					3.18	2.36			

FORKLOCK UPDATED EC NO: S2010-0888 DRWN: JAKEEWEW 2010/04/29 CHKD: CCTEH 2010/06/10 APPR: SHLENI 2010/06/13	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE MM ONLY	SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	$F_A=0$ $F_C=0$ $F_P=0$	mm INCH 4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.2 ± --- 1 PLACE ± --- ± --- ANGULAR ± 1 °	DRAWN BY: YTYANG01 DATE: 2006/08/11 CHECKED BY: SHLENI DATE: 2006/09/07 APPROVED BY: SHLENI DATE: 2010/06/10	TITLE: DDR3 DIMM, 1.00MM PITCH 240 CKTS, VERTICAL T/H			
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	SIZE: A3 THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION	MATERIAL NO. DOCUMENT NO.		MOLEX INCORPORATED SD-78079-001		SHEET NO. 6 OF 8
	A4						

ASSEMBLY PART NO.	VOLTAGE KEY	HOUSING COLOR	LATCH COLOR	DIM 'P'	RECOMMENDED PCB THICKNESS	PLATING OPTION	PRODUCT SPECIFICATION			
78079-0201	CENTRE (1.5V)	BLUE	NATURAL (OFFWHITE)	2.67	1.57	0.38 MICROMETER/ 15 MICROINCH MIN. GOLD ON CONTACT 2.54 MICROMETER/ 100 MICROINCH MIN. PURE TIN ON SOLDER TAILS 1.27 MICROMETER/ 50 MICROINCH MIN. NICKEL UNDERPLATE	PS-78079-001			
78079-0203				3.00	2.18					
78079-0202				3.18	2.36					
78079-0211				2.67	1.57	0.76 MICROMETER/ 30 MICROINCH MIN. GOLD ON CONTACT 2.54 MICROMETER/ 100 MICROINCH MIN. PURE TIN ON SOLDER TAILS 1.27 MICROMETER/ 50 MICROINCH MIN. NICKEL UNDERPLATE		PS-78079-002		
78079-0213				3.00	2.18					
78079-0212				3.18	2.36					
78079-0221		GREEN	NATURAL (OFFWHITE)	2.67	1.57	0.076 MICROMETER/ 3 MICROINCH MIN. GOLD ON CONTACT 2.54 MICROMETER/ 100 MICROINCH MIN. PURE TIN ON SOLDER TAILS 1.27 MICROMETER/ 50 MICROINCH MIN. NICKEL UNDERPLATE	PS-78079-003			
78079-0223				3.00	2.18					
78079-0222				3.18	2.36					
78079-0351				GREEN	NATURAL (OFFWHITE)	2.67		1.57	0.38 MICROMETER/ 15 MICROINCH MIN. GOLD ON CONTACT 2.54 MICROMETER/ 100 MICROINCH MIN. PURE TIN ON SOLDER TAILS 1.27 MICROMETER/ 50 MICROINCH MIN. NICKEL UNDERPLATE	PS-78079-001
78079-0353						3.00		2.18		
78079-0352						3.18		2.36		
78079-0361		GREEN	NATURAL (OFFWHITE)			2.67	1.57	0.76 MICROMETER/ 30 MICROINCH MIN. GOLD ON CONTACT 2.54 MICROMETER/ 100 MICROINCH MIN. PURE TIN ON SOLDER TAILS 1.27 MICROMETER/ 50 MICROINCH MIN. NICKEL UNDERPLATE	PS-78079-002	
78079-0363						3.00	2.18			
78079-0362						3.18	2.36			
78079-0371		GREEN	NATURAL (OFFWHITE)	2.67	1.57	0.076 MICROMETER/ 3 MICROINCH MIN. GOLD ON CONTACT 2.54 MICROMETER/ 100 MICROINCH MIN. PURE TIN ON SOLDER TAILS 1.27 MICROMETER/ 50 MICROINCH MIN. NICKEL UNDERPLATE	PS-78079-003			
78079-0373				3.00	2.18					
78079-0372				3.18	2.36					

FORKLOCK UPDATED EC NO: S2010-0888 DRWN: JAKEEW 2010/04/29 CHKD: CTEH 2010/06/10 APPR: SHLENI 2010/06/13	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE MM ONLY	SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	$F_A=0$ $F_C=0$ $F_P=0$	mm INCH 4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.2 ± --- 1 PLACE ± --- ± --- ANGULAR ± 1 °	DRAWN BY: YTYANG01 DATE: 2006/08/11 CHECKED BY: SHLENI DATE: 2006/09/07 APPROVED BY: SHLENI DATE: 2010/06/10	TITLE: DDR3 DIMM, 1.00MM PITCH 240 CKTS, VERTICAL T/H			
	A4	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	SIZE: A3	MATERIAL NO. DOCUMENT NO. SEE TABLE SD-78079-001		SHEET NO. 7 OF 8	
		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

ASSEMBLY PART NO.	VOLTAGE KEY	HOUSING COLOR	LATCH COLOR	DIM 'P'	RECOMMENDED PCB THICKNESS	PLATING OPTION	PRODUCT SPECIFICATION			
78079-0101	CENTRE (1.5V)	NATURAL (OFFWHITE)	NATURAL (OFFWHITE)	2.67	1.57	0.38 MICROMETER/ 15 MICROINCH MIN. GOLD ON CONTACT 2.54 MICROMETER/ 100 MICROINCH MIN. PURE TIN ON SOLDERTAILS 1.27 MICROMETER/ 50 MICROINCH MIN. NICKEL UNDERPLATE	PS-78079-001			
78079-0103				3.00	2.18					
78079-0102				3.18	2.36					
78079-0111				CENTRE (1.5V)	NATURAL (OFFWHITE)	NATURAL (OFFWHITE)	2.67	1.57	0.76 MICROMETER/ 30 MICROINCH MIN. GOLD ON CONTACT 2.54 MICROMETER/ 100 MICROINCH MIN. PURE TIN ON SOLDERTAILS 1.27 MICROMETER/ 50 MICROINCH MIN. NICKEL UNDERPLATE	PS-78079-002
78079-0113							3.00	2.18		
78079-0112							3.18	2.36		
78079-0121							2.67	1.57	0.076 MICROMETER/ 3 MICROINCH MIN. GOLD ON CONTACT 2.54 MICROMETER/ 100 MICROINCH MIN. PURE TIN ON SOLDERTAILS 1.27 MICROMETER/ 50 MICROINCH MIN. NICKEL UNDERPLATE	PS-78079-003
78079-0123							3.00	2.18		
78079-0122				3.18	2.36					

FORKLOCK UPDATED EC NO: S2010-0888 DRWN: JAKEEWEW 2010/04/29 CHKD: CTEH 2010/06/10 APPR: SHLENI 2010/06/13	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE MM ONLY	SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	$\nabla_A = 0$	4 PLACES	mm INCH	DRAWN BY YTYANG01	DATE 2006/08/11	TITLE DDR3 DIMM, 1.00MM PITCH 240 CKTS, VERTICAL T/H
	$\nabla_C = 0$	3 PLACES	\pm --- \pm ---	CHECKED BY SHLENI	DATE 2006/09/07	 MOLEX INCORPORATED
	$\nabla_P = 0$	2 PLACES 1 PLACE	\pm 0.2 \pm --- \pm --- \pm ---	APPROVED BY SHLENI	DATE 2010/06/10	
A4	DESCRIPTION	ANGULAR \pm 1 °	MATERIAL NO.	DOCUMENT NO.	SHEET NO.	
	REV	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		